

To all our customers

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Renesas Technology Corp.
Customer Support Dept.
April 1, 2003

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Keep safety first in your circuit designs!

1. Renesas Technology Corporation puts the maximum effort into making semiconductor products better and more reliable, but there is always the possibility that trouble may occur with them. Trouble with semiconductors may lead to personal injury, fire or property damage.

Remember to give due consideration to safety when making your circuit designs, with appropriate measures such as (i) placement of substitutive, auxiliary circuits, (ii) use of nonflammable material or (iii) prevention against any malfunction or mishap.

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HD74HC91

8-bit Shift Register



ADE-205-429 (Z)

1st. Edition

Sep. 2000

Description

This serial-in, serial-out, 8-bit shift register is composed of eight R-S master-slave flip-flops, input gating, and a clock drive. Single-rail data and input control are gated through inputs A and B and an internal inverter to form the complementary inputs to the first bit of the shift register. Drive for the internal common clock line is provided by an inverting clock driver. This clock pulse inverter/driver causes these circuits to shift information one bit on the positive edge of an input clock pulse.

Features

- High Speed Operation: t_{pd} (Data Word Input to Output) = 21 ns typ ($C_L = 50$ pF)
- High Output Current: Fanout of 10 LSTTL Loads
- Wide Operating Voltage: $V_{CC} = 2$ to 6 V
- Low Input Current: 1 μ A max
- Low Quiescent Supply Current: I_{CC} (static) = 4 μ A max ($T_a = 25^\circ\text{C}$)

Function Table

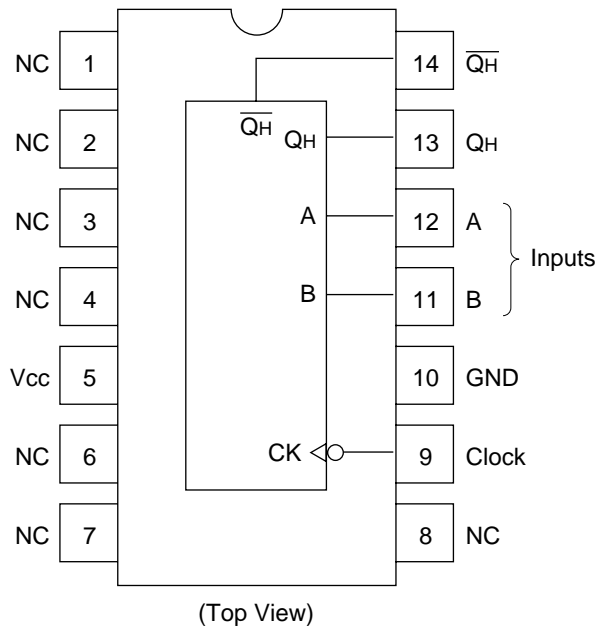
Inputs		Outputs	
t_n		t_{n+8}	
A	B	Q_H	\overline{Q}_H
H	H	H	L
L	X	L	H
X	L	L	H

X : Irrelevant

t_n : Reference bit time, clock low

t_{n+8} : Bit time after 8 low-to-high clock transitions

Pin Arrangement



DC Characteristics

Item	Symbol	V _{CC} (V)	Ta = 25°C		Ta = -40 to +85°C		Unit	Test Conditions		
			Min	Typ	Max	Min			Max	
Input voltage	V _{IH}	2.0	1.5	—	—	1.5	—	V		
		4.5	3.15	—	—	3.15	—			
		6.0	4.2	—	—	4.2	—			
	V _{IL}	2.0	—	—	0.5	—	0.5	V		
		4.5	—	—	1.35	—	1.35			
		6.0	—	—	1.8	—	1.8			
Output voltage	V _{OH}	2.0	1.9	2.0	—	1.9	—	V	Vin = V _{IH} or V _{IL} I _{OH} = -20 μA	
		4.5	4.4	4.5	—	4.4	—			
		6.0	5.9	6.0	—	5.9	—			
		4.5	4.18	—	—	4.13	—			I _{OH} = -4 mA
		6.0	5.68	—	—	5.63	—			I _{OH} = -5.2 mA
	V _{OL}	2.0	—	0.0	0.1	—	0.1	V	Vin = V _{IH} or V _{IL} I _{OL} = 20 μA	
		4.5	—	0.0	0.1	—	0.1			
		6.0	—	0.0	0.1	—	0.1			
		4.5	—	—	0.26	—	0.33			I _{OL} = 4 mA
		6.0	—	—	0.26	—	0.33			I _{OL} = 5.2 mA
Input current	I _{in}	6.0	—	—	±0.1	—	±1.0	μA	Vin = V _{CC} or GND	
Quiescent supply current	I _{CC}	6.0	—	—	4.0	—	40	μA	Vin = V _{CC} or GND, I _{out} = 0 μA	

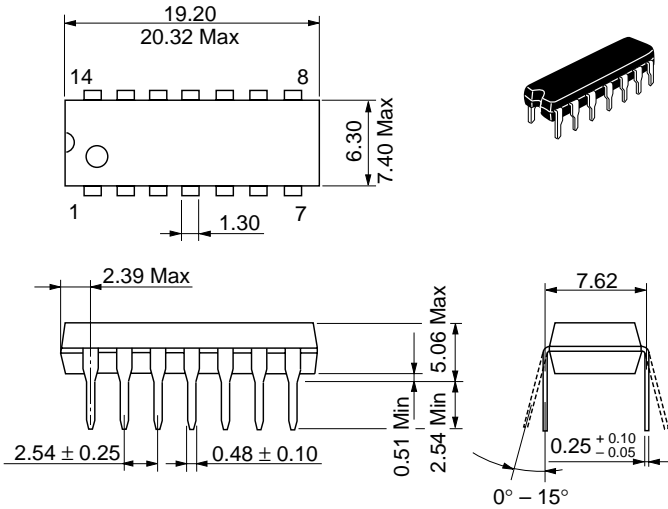
HD74HC91

AC Characteristics ($C_L = 50$ pF, Input $t_r = t_f = 6$ ns)

Item	Symbol	V_{CC} (V)	$T_a = 25^\circ\text{C}$		$T_a = -40$ to $+85^\circ\text{C}$		Unit	Test Conditions	
			Min	Typ	Max	Min			Max
Maximum clock frequency	f_{max}	2.0	—	—	5	—	4	MHz	
		4.5	—	—	25	—	20		
		6.0	—	—	29	—	24		
Propagation delay time	t_{PLH}	2.0	—	—	210	—	265	ns	
		4.5	—	21	42	—	53		
		6.0	—	—	36	—	45		
	t_{PHL}	2.0	—	—	210	—	265	ns	
		4.5	—	21	42	—	53		
		6.0	—	—	36	—	45		
Pulse width	t_w	2.0	125	—	—	156	—	ns	Clock
		4.5	25	9	—	31	—		
		6.0	21	—	—	26	—		
Set up time	t_{su}	2.0	125	—	—	156	—	ns	
		4.5	25	1	—	31	—		
		6.0	21	—	—	26	—		
Hold time	t_h	2.0	5	—	—	5	—	ns	
		4.5	5	-1	—	5	—		
		6.0	5	—	—	5	—		
Output rise/fall time	t_{TLH}	2.0	—	—	75	—	95	ns	
	t_{THL}	4.5	—	5	15	—	19		
		6.0	—	—	13	—	16		
Input capacitance	C_{in}	—	—	5	10	—	10	pF	

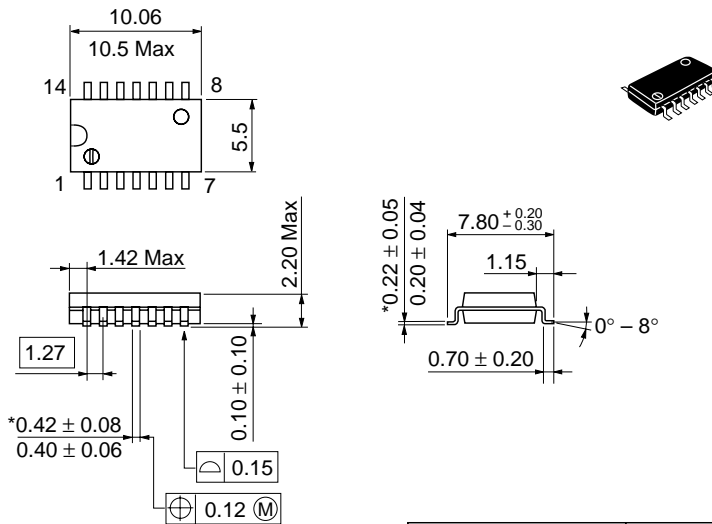
Package Dimensions

Unit: mm



Hitachi Code	DP-14
JEDEC	Conforms
EIAJ	Conforms
Mass (reference value)	0.97 g

Unit: mm

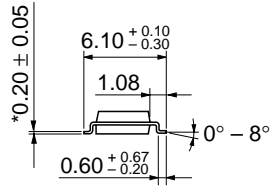
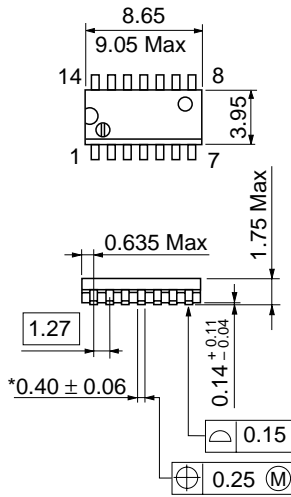


Hitachi Code	FP-14DA
JEDEC	—
EIAJ	Conforms
Mass (reference value)	0.23 g

*Dimension including the plating thickness
Base material dimension

HD74HC91

Unit: mm



*Pd plating

Hitachi Code	FP-14DN
JEDEC	Conforms
EIAJ	Conforms
Mass (reference value)	0.13 g

Cautions

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